

Appl. No. 10/823,098
Amdt. dated 09/17//2007
Reply to Office action of 08/22/2007

Amendment of the Abstract

Please replace the current abstract with the following new abstract:

A method to dissipate heat from a coil located within a micro-structure is disclosed. By thermally contacting the coil with a heat diffuser that is thermally connected to the substrate through a thermally conductive pedestal, efficient transfer of heat from the coil to the substrate is facilitated.